

# Technical Data Sheet



**Culver International Ltd**

**Dynaloy European Manufacturers Agent**

Establishing Distributors and Maintaining  
The European Network for Dynaloy, Inc.



**Engineered Chemistries**

**ISO 9001:2000**

## DYNASOLVE CU-9

### **General:**

NON-FLAMMABLE SOLVENT FOR CLEANING RELEASE AGENTS. Dynasolve CU-9 is a high flash point proprietary solvent system designed to remove both uncured and cured silicone release agents from metal molds. Dynasolve CU-9 is very effective in the polyurethane molding industry and the baking industry. Dynasolve CU-9 also dissolves RTV silicones and polyamide-based adhesives. The product is a non-chlorinated, nonflammable, non-carcinogenic, non-ozone depleting solvent designed to replace solvents such as methylene chloride and 1,1,1-trichloroethane in cleaning silicone mold release build-up. Dynasolve CU-9 is much safer than the above mentioned chlorinated solvents and friendlier to the environment. It can be used for extended periods, tolerates a high resin loading and will reduce disposal costs. In addition, Dynasolve CU-9 is recyclable using vacuum distillation.

### **Applications:**

1. For the polyurethane molding industry, it removes built-up silicone and polyurethane residue by breaking the bond to the metal mold so that the mold can be cleaned by a gentle brushing action.
2. For the baking industry, it removes the cured silicone release glaze and baked residue from the pan by dissolving the outer layers, then penetrating the metal bonding layer and lifting it to enable easy removal of the silicone release agent.
3. Dynasolve CU-9 dissolves RTV silicones.
4. Dynasolve CU-9 dissolves polyamide-based hot melt adhesives.

### **Specifications:**

Color	water white to slight amber
Specific Gravity	0.98
Boiling Point	>400 F
Flash Point	210 F

### **Directions For Use:**

1. Dynasolve CU-9 works slowly at room temperature, but much faster at 225-250°F.
2. Pour solvent into metal container (preferably stainless steel) and immerse mold.
3. If mold is too large for immersion, bring mold to 250°F and pour warm solvent (125-150°F) into mold.
4. For the baking industry, if pans can not be easily immersed, place warm solvent into hot pans.
5. The residue should brush off in less than one hour.
6. Dynasolve CU-9 can be rinsed off mold or pan surface with water or detergent and water.

### **Materials of Construction:**

Recommended – Teflon, EPDM, Kalrez, Mild Steel, Polypropylene

Avoid – Viton, PVC, ABS, Buna N, Kynar Zefan, Noryl EN265, PET, Butyl Rubber

### **Caution:**

Dynasolve CU-9 is a reactive solvent and proper precautions must be observed. Please refer to MSDS before use or disposal.

The information in this sheet is based upon our own research and is considered accurate. However, we make no warranty either expressed or implied regarding accuracy and results to be obtained, because operating conditions of users are beyond our control.

Last Revised By: Lauri Kirby  
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